

Copper-Barrier MLCC



Micross Components in partnership with Syfer Technology are now offering MLCC capacitors with Cu Terminations.

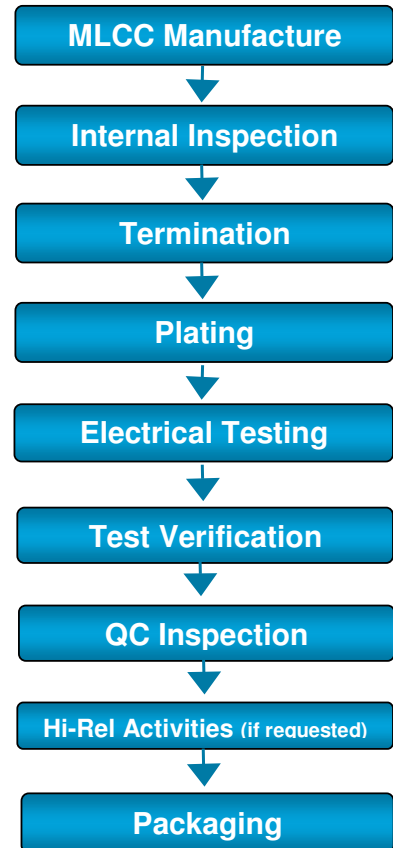
Copper barrier terminations with a tin finish on top have a number of benefits:

- RoHS compliant
- No solder leaching
- Fully non-magnetic component
- Selected C0G/NP0, High Q & X7R dielectrics
- C0G-NP0 dielectrics supplied with sintered terminations for 260°C soldering
- X7R supplied with Syfer award-winning FlexiCap™ termination

Features

	<u>C0G/NP0</u>	<u>High-Q</u>	<u>X7R</u>
Capacitance Values	0.1pF to 15nF	0.1pF to 15nF	47pF to 6.8µF
Operating Temp	-55°C to +125°C	-55°C to +125°C	-55°C to +125°C
Temp Coefficient	0±30ppm/°C	0±30ppm/°C	±15%
Insulation Resistance Time Constant (Ri x Cr) (whichever is the least)	100GΩ or 1000s	100GΩ or 1000s	100GΩ or 1000s
Ageing Rate	None	None	<2% per time decade

Syfer Process Flow

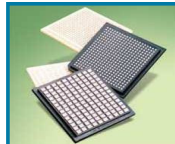
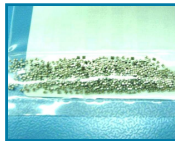


Shipping methods include:

- Bulk Pack – Tubs
- Bulk Pack – Bags

- Waffle Packs
- Gel Pack

- 7" Tape & Reel
- 13" Tape & Reel



Applications:

- MRI
- Medical test & Diagnostic equipment
- High Rel Medical Systems
- High Rel Aviation Systems
- Laboratory Analysis Systems
- Navigation & Electronic test equipment

For further information regarding the extensive range Micross supports, please go to <http://www.micross.com/distribution.aspx> or email chipcomponents@micross.com